

ABSTRACT

A MEMS device can prevent protrusion of a metal from a bonding surface in eutectic bonding.

The MEMS device includes a lower substrate having an element having wiring on a surface thereof; an upper substrate provided so as to be opposed to the element; and a bonding section that bonds the lower substrate and the upper substrate to each other on the periphery of the element. The bonding section has a first region, a second region, and a third region which are sequentially provided in this order from a side closer to the element to a side farther from the element. At least one of the first region and the third region contains a hyper-eutectic alloy of one of a first component and a second component, which has a higher melting point, and the second region contains a eutectic alloy of the first component and the second component.